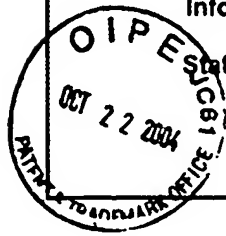


Form 1449 (Modified)	Atty. Docket No.: NNEX0012C	Serial No.: 10/717, 813
Information Disclosure Statement By Applicant	Applicant: Mok et al	Examiner: Unassigned TRUNG NGUYEN
	Filing Date: November 19, 2003	Group: 2829



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8/27/05.